		Integrated Device Technology, Inc. 6024 Silver Creek Valley Road San Jose, CA 96138 DUICT/PROCESS CHANGE NOTICE (PCN)					
			Mov 8 2000	MEANS OF DISTRICUSIONS CHANCED	DEVICES		
PCN #: A0903-0	0 mm = 0 === 1/	AIE:	wiay 8, 2009	INIEANS OF DISTINGUISHING CHANGED I	DEVICES:		
Product Affected:	9 mm x 9 mm V	rqfpn-64			~		
10 mm x 10 mm VFQFPN-72			72	Back Mark Lot # will have a "Y" suf	tix		
				□ Date Code			
				□ Other			
Date Effective: Au	ugust 8, 2009						
Contact: Bimla	Paul			Attachment: Yes No			
Title: Produ	ct Quality Assurat	nce					
Phone #: (408)	574-6419			Samples: Contact your local IDT sales representative for sample			
Fax #: (408)	284-8362			requests.			
E-mail: <u>Bimla</u>	.Paul@idt.com						
DESCRIPTION AN	D PURPOSE OF	CHANGE	E:				
Die Technology			This notification	is to advise our customers that IDT is adding Car	sem, Malaysia		
□ Wafer Fabrication Process			(9 mm x 9 mm	(9 mm x 9 mm VFQFPN-64) and Chipmos, Taiwan (9 mm x 9 mm VFQFPN-64			
Assembly Process Equipment			and 10 mm x 10	and 10 mm x 10 mm VFQFPN-72) as alternate assembly facilities for Copper			
 Equipment Material 			Bond Wire proc	ess.			
□ Testing			A follow-up notification with complete qualification data will be sent prior to first				
Manufacturing Si	Manufacturing Site customer shipment.			Prior to mot			
Data Sheet			L				
□ Other		Attachment 1 ou Attachment 2 sh	Attachment 1 outlines the qualification plans and results. Attachment 2 shows all the affected part numbers.				
RELIABILITY/QU	JALIFICATION	SUMMAR	Y:				
Please refer to qualit	fication data in At	tachment 1					
CUSTOMER ACK	NOWLEDGME	NT OF RE	CEIPT:				
IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail							
to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice							
it will be assumed the	hat this change is	acceptable.					
IDT reserves the rig	ht to ship either v	ersion manu	ufactured after the p	process change effective date until the inventory			
on the earlier versio	on has been deplete	ed.					
Customer:			_ C	Approval for shipments prior to effective of	date.		
Name/Date:			F	E-Mail Address:			
Title:			F	hone# /Fax# :			
CUSTOMER COM	IMENTS:						
IDT ACKNOWLE	DGMENT OF R	ECEIPT:					
RECD. BY:				DATE:			
IDT FRA-1509-01	REV. 00 09/18/0	1	Page	e 1 of 1 R	efer To QCA-1795		



Integrated Device Technology, Inc. 6024 Silver Creek Valley Road San Jose, CA 96138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 1 - PCN # : A0903-04

PCN Type:Manufacturing Site & Material - Alternate Assembly Location & Copper Bond WireData Sheet Change:NoneDetail Of Change:Image: Comparison of Change (Comparison of Comparison of Compar

This notification is to advise our customers that IDT is adding Carsem, Malaysia (9 mm x 9 mm VFQFPN-64) and Chipmos, Taiwan (9 mm x 9 mm VFQFPN-64 and 10 mm x 10 mm VFQFPN-72) as alternate assembly facilities for Copper Bond Wire process.

IDT has already successfully qualified Copper wire bond process and has been shipping products assembled at PT Unisem, Indonesia for 9 mm x 9 mm VFQFPN-64 package type, and Carsem, Malaysia and PT Unisem, Indonesia for 10 mm x 10 mm VFQFPN-72 package type.

Copper bond wire process is presently used by selective semiconductor suppliers due to the following key advantages:

A. Better electrical performance- higher current handling capability - 18% improvement in resistance for 1 mil bond wire.

- B. Better high temperature bake performance. Minimal intermettalic compound build up.
- C. Higher Ball shear and wire pull test result- smaller bond pad real estate is now possible.
- D. Stiffer Wire- minimize wire swaying , longer wires than gold is now possible.

A follow-up notification with complete qualification data will be sent prior to first customer shipment.

Customers may expect to receive shipments with Cu wire process no sooner than 90 days from the date of this notification, May 8, 2009. Product assembled with Au and Cu wire will be shipped during the transition period or until the Au wire inventory has been depleted. Please note that product assembled with Au and Cu wire will not be mixed in one tray stack, or tape and reel.

We request you to acknowledge receipt of this notification within 30 days of the date of this PCN notification. If you require samples to conduct evaluations, please make your sample request within 30 days as samples are not built ahead of the change for all device options. You may contact your local sales representative to acknowledge this PCN and request samples.



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 1 - PCN # : A0903-04

Assembly Material : There is no change in the mold compound and die attach materials. The material sets used in assembly is in compliance with RoHS 5 (standard products) and RoHS 6 (green products) requirement. There is no change in the moisture sensitivity performance.

Sample Availability : Samples are not built ahead of the change for all device types and may not be available for all affected device types.

Please contact your local IDT sales representative for your sample request and availability.

Qualification Test Plans and Results :

1. Copper Bond Wire Qual Results

Qual Vehicle: i) 10 mm x 10 mm VFQFPN-72, Carsem, Malaysia ii) 10 mm x 10 mm VFQFPN-72, Chipmos, Taiwan

		Test R (SS /	lesults Rej)
Test Description	Test Method	Carsem, Malaysia	Chipmos, Taiwan
* High Accelerated Stress Test (Biased, 130 °C/85% RH, 100 Hrs)	JESD22-A110	45/0	
* Temperature Cycle / Condition B (-55 °C to +125 °C, 1000 Cyc)	JESD22-A104	¹ 44/0	
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	77/0	Expected completion date
Ball Shear Test	JESD22-B116	5/0	June 1, 2009
Wire Bond Pull Test	Mil-Std-883 M2001	5/0	
X-ray Examination	IDT Spec MAC-3012	45/0	

Note:

* Test requires moisture pre-conditioning sequence per JESD22-A113C and will use the existing moisture sensitivity level that has been qualified for this material set.

¹ One unit functional die level failure, not related to Cu bond wire process

2. Product Electrical Characterization

Product electrical characterization has been successfully completed on representative product families and copper wire performance was comparable to gold wire performance.



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 2 - PCN # : A0903-04

Affected Device

Device	Device	Device	Device
954305	9LPRS114	9LPRS395	9LPRS918
954309	9LPRS133	9LPRS397	9LPRS919
9LPR309	9LPRS138	9LPRS470	9LPRS928
9LPR311	9LPRS139	9LPRS471	9LPRS929
9LPR323	9LPRS140	9LPRS472	9LRS3165
9LPR325	9LPRS319	9LPRS474	9LRS3166
9LPR332	9LPRS325	9LPRS476	9LRS4880
9LPR333	9LPRS333	9LPRS477	9LVRS129
9LPR335	9LPRS353	9LPRS478	9LVRS130
9LPR336	9LPRS355	9LPRS480	CLK503J45
9LPR350	9LPRS356	9LPRS488	CV153
9LPR390	9LPRS357	9LPRS501	CV169
9LPR800	9LPRS365	9LPRS910	CV171
9LPR802	9LPRS387	9LPRS911	CV179
9LPRS110	9LPRS390	9LPRS914	
9LPRS113	9LPRS392	9LPRS915	